

45V N-Channel SGT MOSFET

General Description

- Trench Power SGT technology
- Very low on-resistance R_{DS(ON)}
- Low Gate Charge
- Excellent Gate Charge x R_{DS(ON)} Product

Applications

• High Frequency Switching and Synchronous Rectification

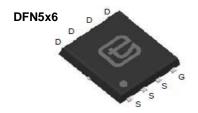
Product Summary

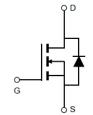
 $\begin{array}{lll} V_{DS} & 45V \\ I_{D} \left(\text{at } V_{GS} \!=\! 10V \right) & 100A \\ R_{DS(ON)} \left(\text{at } V_{GS} \!=\! 10V \right) & < 1.7 \text{m}\Omega \end{array}$

 $R_{DS(ON)}$ (at V_{GS} =4.5V) < 2.4m Ω

100% DVDS Tested 100% UIS Tested 100% Rg Tested







Part Number Package Type		Form	Marking	
TSG017N045AT	DFN5x6	Tape & Reel	TSG017N045AT	

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V _{DS}	45	V	
Gate-Source Voltage		V _{GS}	±20	V	
Continuous Drain Current B	T _C =25°C	,	100 (package limited)	Λ	
Continuous Drain Current B	T _C =100°C	I _D	100 (package limited)	Α	
Pulsed Drain Current A		I _{DM}	400	Α	
Avalanche Current ^A		I _{AS}	58	Α	
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	504.6	mJ	
Power Dissipation ^C	T _C =25°C	D	125	W	
	T _C =100°C	P _D	50	W	
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C	

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	1.0	°C/W	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	50		



Symbol	Parameter	rameter Conditions		Value			Units
Зуппоп	raiametei			Min	Тур	Max	Onits
STATIC P	ARAMETERS					_	
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		45			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =45V, V _{GS} =0V	T _J =25°C T _J =125°C			1 100	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	<u> </u>			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.6	2.4	V	
R _{DS(ON)} Static Drain-Source On-Resistance		V _{GS} =10V, I _D =30A		1.5	1.7	mΩ	
	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =30A		2	2.4	mΩ	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A			56.8		S
V _{SD}	Diode Forward Voltage	I _S =30A, V _{GS} =0V			1	V	
I _s	Maximum Body-Diode Continuous Curre	nt ^B			100	Α	
DYNAMIC	PARAMETERS					•	
C _{iss}	Input Capacitance				5096		
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 1MH_{Z}$			1213		pF
C _{rss}	Reverse Transfer Capacitance]		140		
R_g	Gate Resistance	f =1MH _Z		3.4		Ω	
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge				82		
Q _g (4.5V)	Total Gate Charge	\/ _10\/\/ _20\/\	-204		38		
Q_{gs}	Gate Source Charge	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 20A$			16		nC
Q_{gd}	Gate Drain Charge				12		
Q _{oss}	Output Charge	V _{GS} =0V,V _{DS} =20V			49.6		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 20A,$ $R_{G} = 1.6\Omega$			26		ns
t _r	Turn-On Rise Time				5		
$T_{D(off)}$	Turn-Off Delay Time				47		
t _f	Turn-Off Fall Time				10.5		
t _{rr}	Body Diode Reverse Recovery Time	1 -20A di/dt -400A/			35		ns
Q _{rr}	Body Diode Reverse Recovery Charge	-I _F =20A, di/dt =100A/μs			78		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

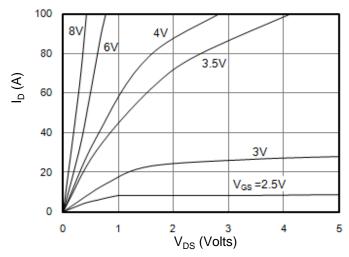


Figure 1: On-Region Characteristics

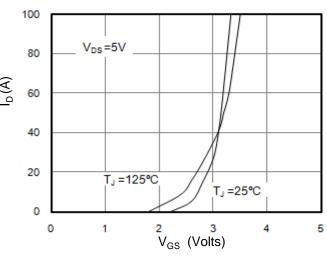


Figure 2: Transfer Characteristics

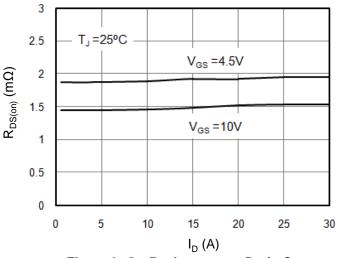


Figure 3: On-Resistance vs. Drain Current

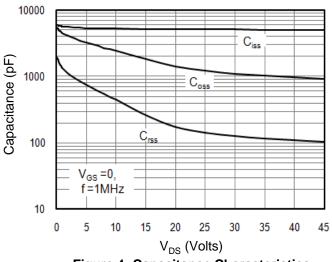


Figure 4: Capacitance Characteristics

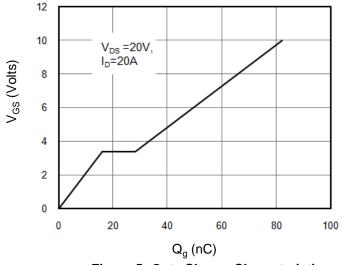


Figure 5: Gate Charge Characteristics

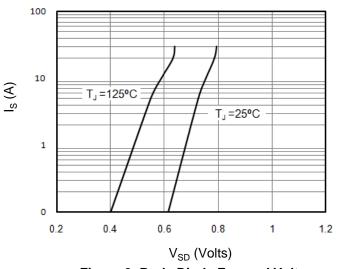


Figure 6: Body Diode Forward Voltage

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

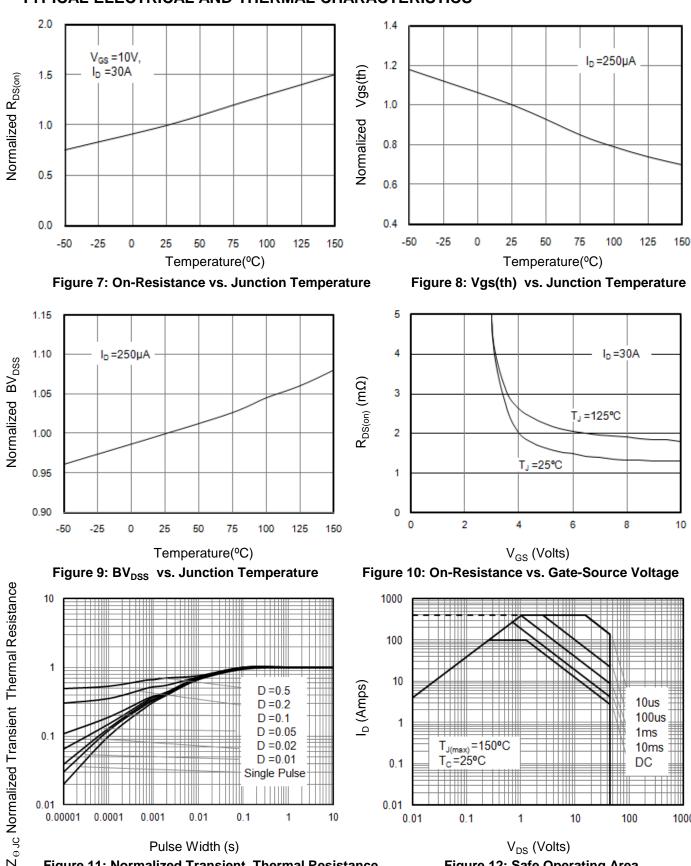


Figure 11: Normalized Transient Thermal Resistance

Pulse Width (s)

0.00001

0.0001

V_{DS} (Volts) Figure 12: Safe Operating Area

10

100

1000

10

0.01

0.1



Figure A: Gate Charge Test Circuit and Waveforms

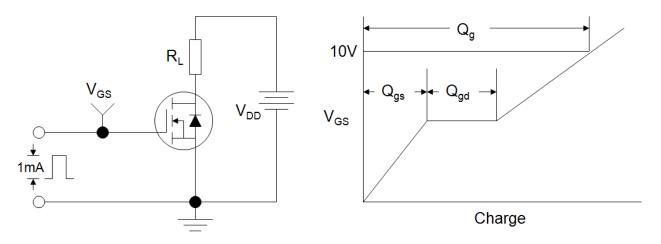


Figure B: Resistive Switching Test Circuit and Waveforms

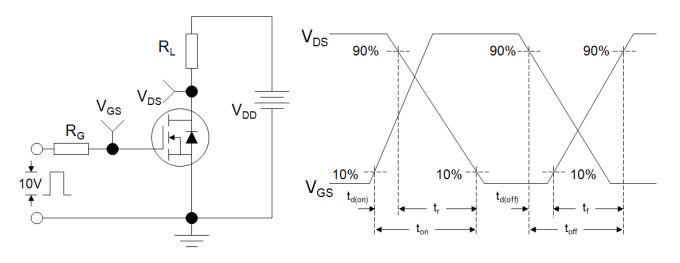
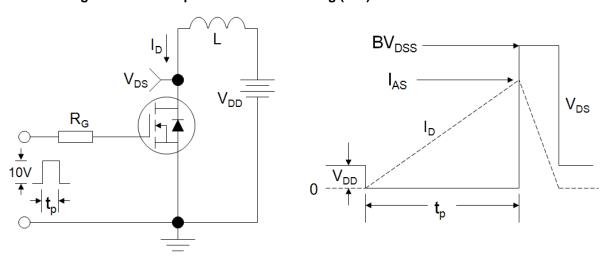
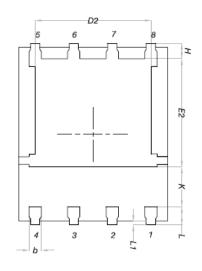


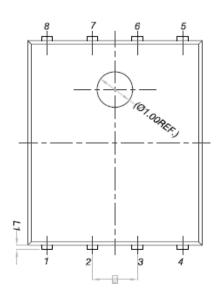
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms

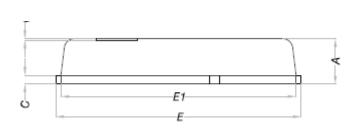


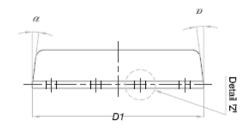


DFN5x6









5/14	MILLIMETERS		D/M	MILLIMETERS			
DIM.	MIN.	NOM.	MAX.	DIM.	MIN.	NOM.	MAX.
Α	0.90	1.00	1.10	E	5.90	6.00	6.10
A1	0	-	0.05	E1	5.70	5.75	5.80
b	0.33	0.41	0.51	E2	3.38	3.58	3.78
С	0.20	0.25	0.30	е	1.27 BSC		
D1	4.80	4.90	5.00	Н	0.41	0.51	0.61
D2	3.61	3.81	3.96	K	1.10	-	-
				L	0.51	0.61	0.71
				L1	0.06	0.13	0.20
				α	O°	-	12°



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